



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-05-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STF35N60DM2	XSPF*FQ6KB32	A	3068	2017-05-18
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.15-4.5	3	Through-hole	
Comment	TO 220 ISO FULL PACK IN LINE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.81	Die back side metal Leadframe metal	428
Lead	17.77	Soft solder	9354

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	XSPF*FQ6KB32					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	20.783	mg	supplier	die	Silicon (Si)	7440-21-3		19.943	mg	959582	10496
				supplier	metallization	Aluminium (Al)	7429-90-5		0.403	mg	19391	212
				supplier	Passivation	Silicon Nitride	12033-89-5		0.096	mg	4619	51
				supplier	Passivation	Silicon Oxide	7631-86-9		0.143	mg	6881	75
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.010	mg	481	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.139	mg	6688	73
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.049	mg	2358	26
				supplier	alloy	Copper (Cu)	7440-50-8		604.469	mg	997498	318142
				supplier	alloy	Iron (Fe)	7439-89-6		0.605	mg	998	318
Leadframe	Copper & its alloys	605.985	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.182	mg	300	96
				supplier	alloy	Nickel (Ni)	7440-02-0		0.674	mg	1113	354
				supplier	metallization	Phosphorus (P)	12185-10-3		0.055	mg	91	29
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	17.772	mg	955022	9354
				supplier	solder	Silver (Ag)	7440-22-4		0.465	mg	24988	245
Soft solder	Solder	18.609	mg	supplier	solder	Tin (Sn)	7440-31-5		0.372	mg	19990	196
				supplier	wire	Aluminium (Al)	7429-90-5		1.080	mg	996310	568
				supplier	wire	Magnesium (Mg)	7439-95-4		0.004	mg	3690	2
Encapsulation	Other Organic Materials	1247.673	mg	supplier	mold compound	Quartz	14808-60-7		873.371	mg	700000	459669
				supplier	mold compound	Silica, vitreous	60676-86-0		93.576	mg	75000	49251
				supplier	mold compound	Epoxy resin	25068-38-6		174.674	mg	140000	91934
				supplier	mold compound	phenol resin	29690-82-2		87.337	mg	70000	45967
				supplier	mold compound	metal hydroxide	Proprietary		12.477	mg	10000	6567
				supplier	mold compound	carbon black	1333-86-4		6.238	mg	5000	3283
Connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087